



Towards energy-saving chips for digital, analog, RF

The FAMES Pilot Line of the Chips JU is funded by Horizon Europe and Digital Europe Programmes and the National Public Authorities of the partners involved.



BUSINESS
FINLAND

Ministry of Science and Higher Education
Republic of Poland



Bundesministerium
Klimaschutz, Umwelt,
Energie, Mobilität,
Innovation und Technologie



Member of
UAR INNOVATION
NETWORK

LAND KÄRNTEN

Das Land
Steiermark



FEEI



ZUKUNFTSFONDS
STEIERMARK

PERTE
Chip

■ Aim & Status

- The FAMES Pilot Line will provide **opportunities for disruptive chips architecture** with performance improvement and significant energy savings
- All Pilot Line agreements completed in December 2024, project is running at full speed (procurements, R&D programs, communication & dissemination)
- First Open Access call (request for Access) in March 2025

Consortium



FAMES Pilot Line Consortium

- Hosting sites
- Skills contributors

Budget : €830 M

- CAPEX: €382 M
- OPEX: €448 M

Funding:


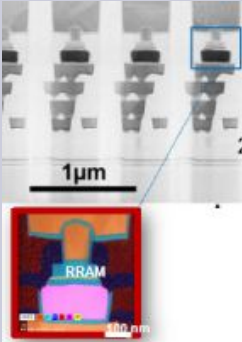

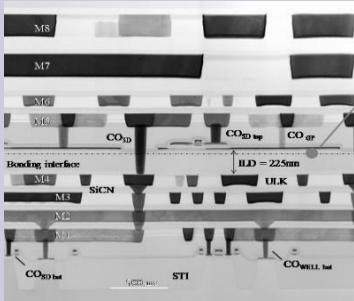
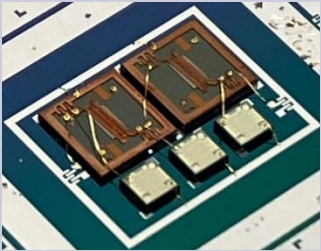





- 50% Chips JU
- 50% Member States



fames-pilot-line.eu



FAMES Technological Portfolio

FD-SOI	Embedded non-volatile memories	Radiofrequency components	3D integration	Small inductors for DC-DC converters
<p>10 nm and 7 nm nodes</p>  <p>0,7V 57CPP 48/40MPP</p>	<p>OxRAM, FeRAM, MRAM and FeFET</p> 	<p>Switches, filters, and capacitors</p> 	<p>Heterogeneous and sequential</p> 	<p>Power management integrated circuits (PMIC)</p> 
				

Opening the Pilot Line to European stakeholders

44 support letters





Accessing the FAMES Pilot Line



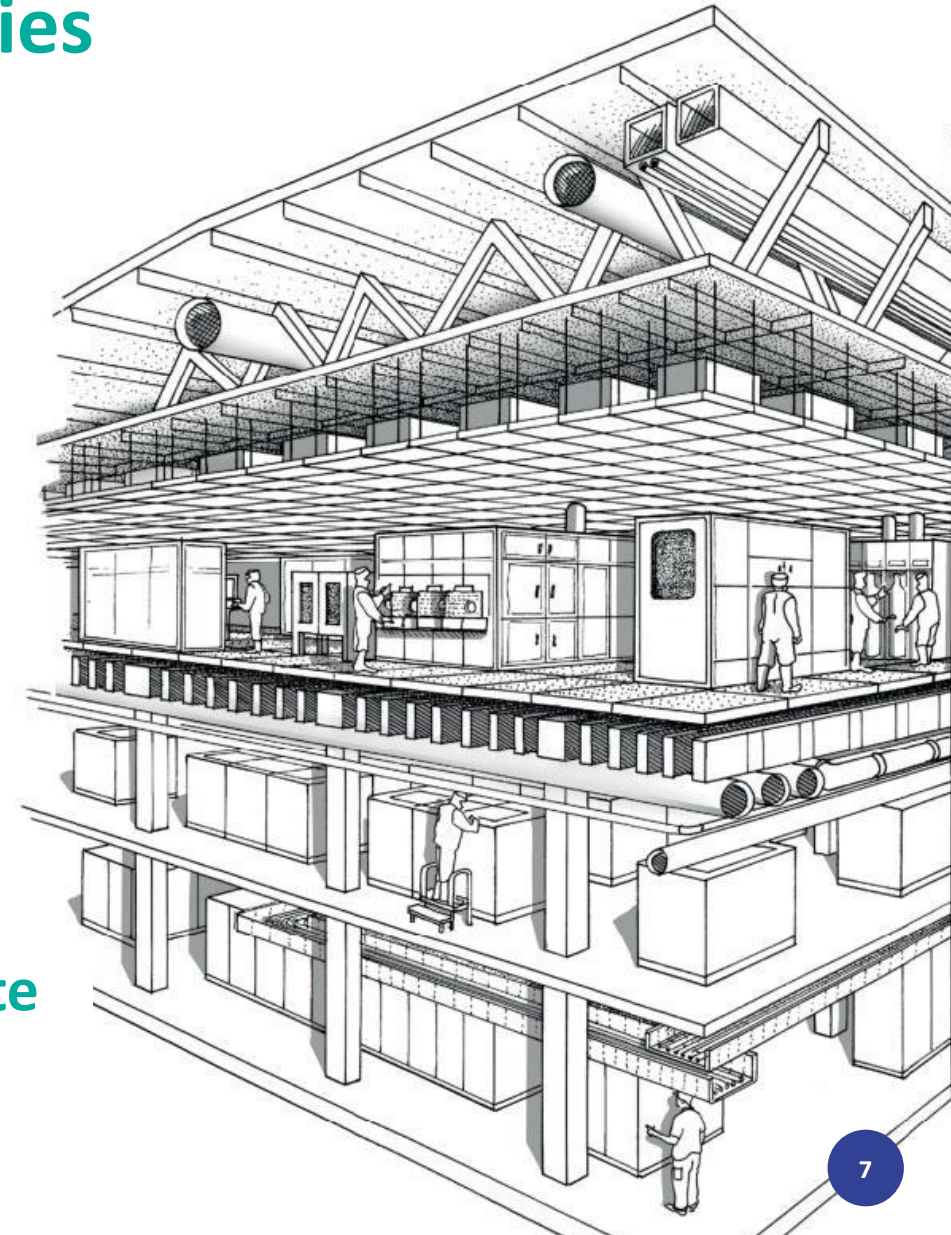
FAMES European open-access pilot line for advanced semiconductor technologies

To gain access to:

- Two types of PDKs (multi-project wafer or IC design assessment)
- The FAMES technologies (FD-SOI 10 nm and 7 nm, embedded non-volatile memories, RF components, 3D integration options) for performance evaluation
- Specific process steps, modules, integration flows, and demonstrator results
- Education and training on the FAMES technologies

as they become available

□ Request an access to the Pilot Line and receive a quote



The FAMES Pilot Line is open to all types of Users



LARGE COMPANIES



SMEs



START-UPS



RESEARCH COMMUNITY



Design Houses

Fabless

Foundries

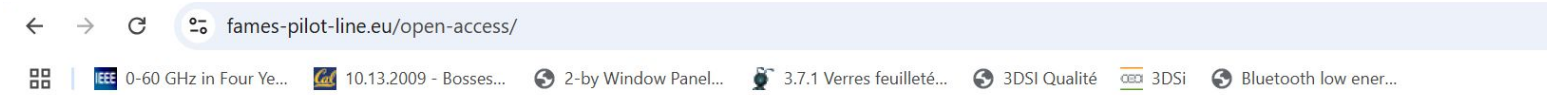
Integrated Device Manufacturers

Material and Tool Suppliers

Universities

Research Centers

Open Access calls: request for Access to the Pilot Line



OPEN ACCESS

FAMES Pilot Line

The FAMES pilot line offers European semiconductor stakeholders from industry, research, and academia access to a wide range of semiconductor technologies, including testing, PDKs, demonstrators and manufacturing capabilities.

FAMES
greener electronics
FD-SOI · NVM · 3D · RF · PMIC

Title: FAMES Pilot Line User Guidelines and Procedures
Author: S. Bonnetier et al
Version: 07

FAMES PILOT LINE USER GUIDELINES AND PROCEDURES

Project Number	101182279	Project Acronym	FAMES
Project Title	FD-SOI Pilot Line for Applications with embedded non-volatile Memories, RF, 3D integration and PMIC, to ensure European Sovereignty		



Open calls

The first call should open by the spring of 2025. You will find the submission details on this page as soon as the call is open.

Forthcoming Key Dates

Mid-March, 2025

**FAMES Pilot Line
Open Call
(Request for Access)**
Online opening



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March 18, 2025

**FAMES Dedicated
Workshop**
Launch of the 1st open call
Brussels, Belgium



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June 19, 2025

**FAMES
School**
Initial training
Grenoble, France



leti-innovation-days.com

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